

# Printed Circuit Board Design Updates

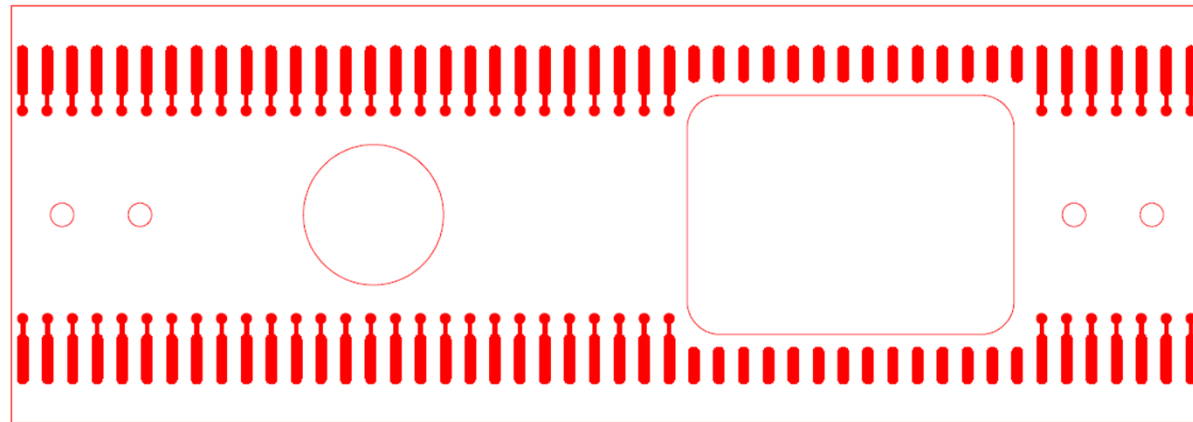
Andrew Landrie and Xu Zhai  
UW Physical Sciences Laboratory  
March 27, 2019

# Design Updates – Overview

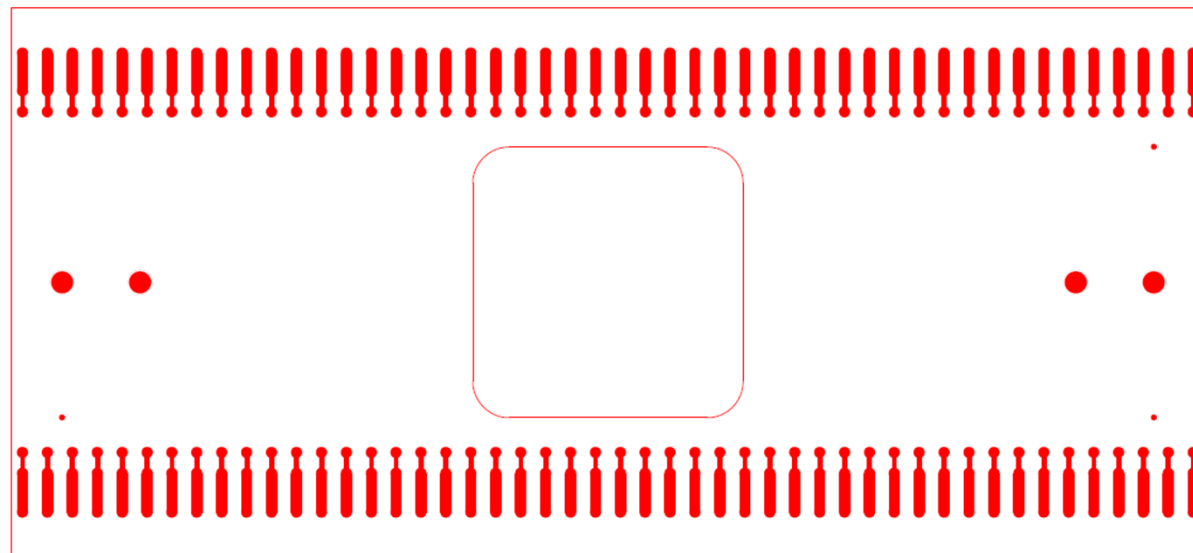
- Foot Boards and Side Boards
  - Dimensions stretched to fit larger frame tubes
  - Multi-layer boards are required in some locations
- Head Boards
  - Increased spacing between wire traces
  - Improved interface for electrical testing
- Hardware Improvements
  - Custom Mill-Max sockets and pins
  - Stronger threaded inserts in boards

# X-Layer Foot Boards

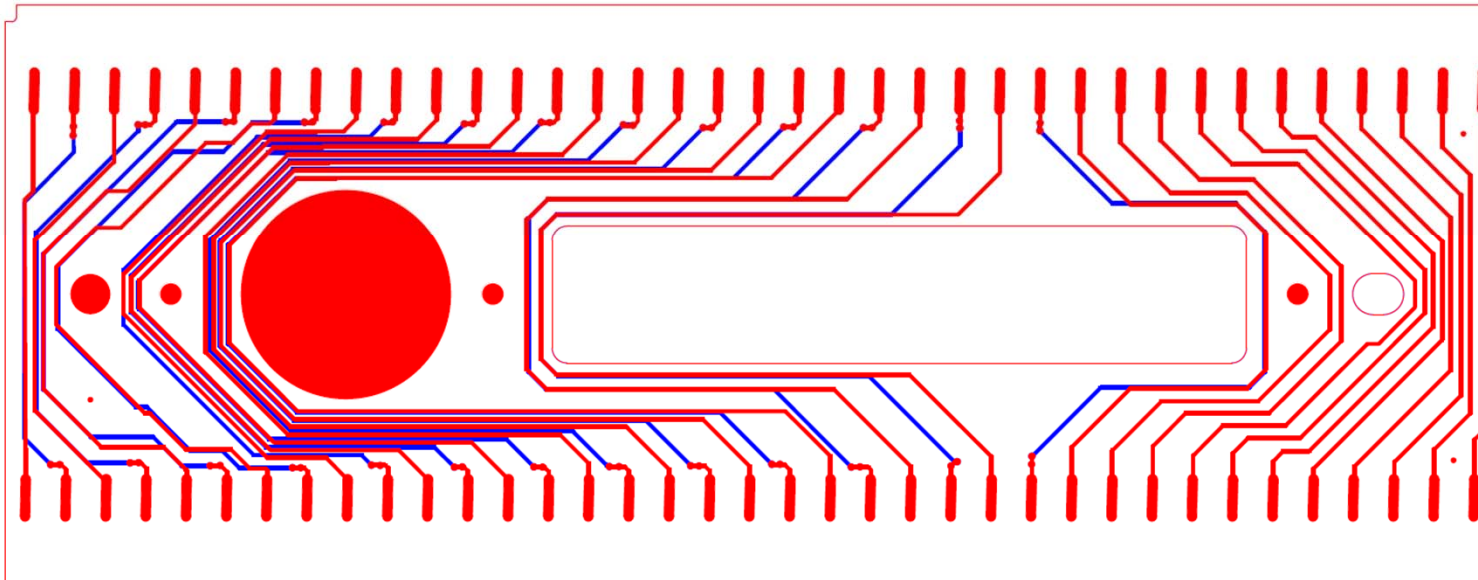
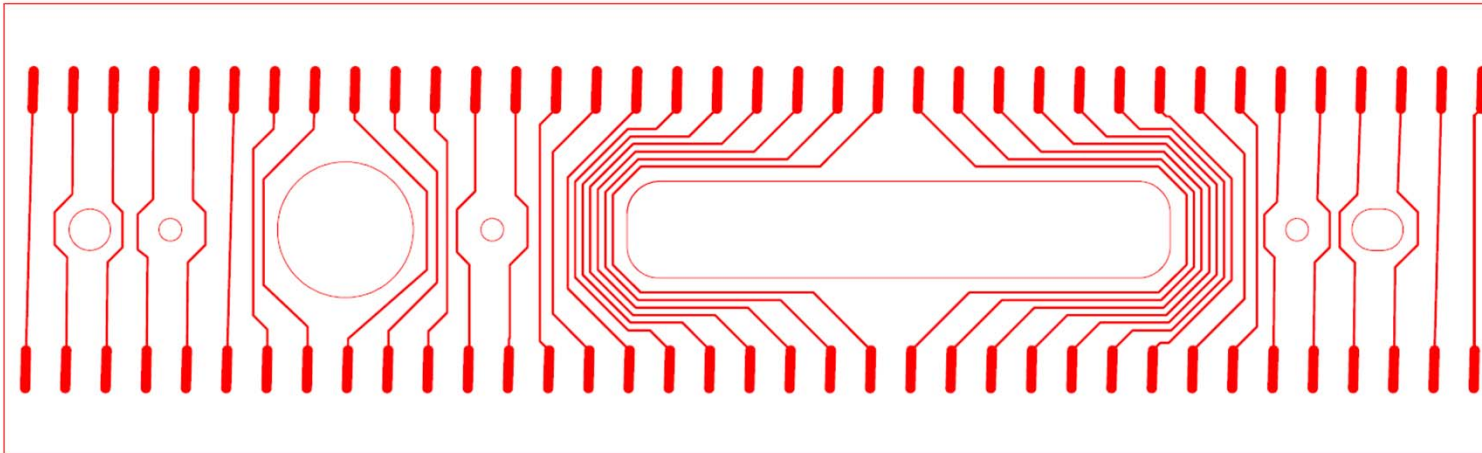
Old



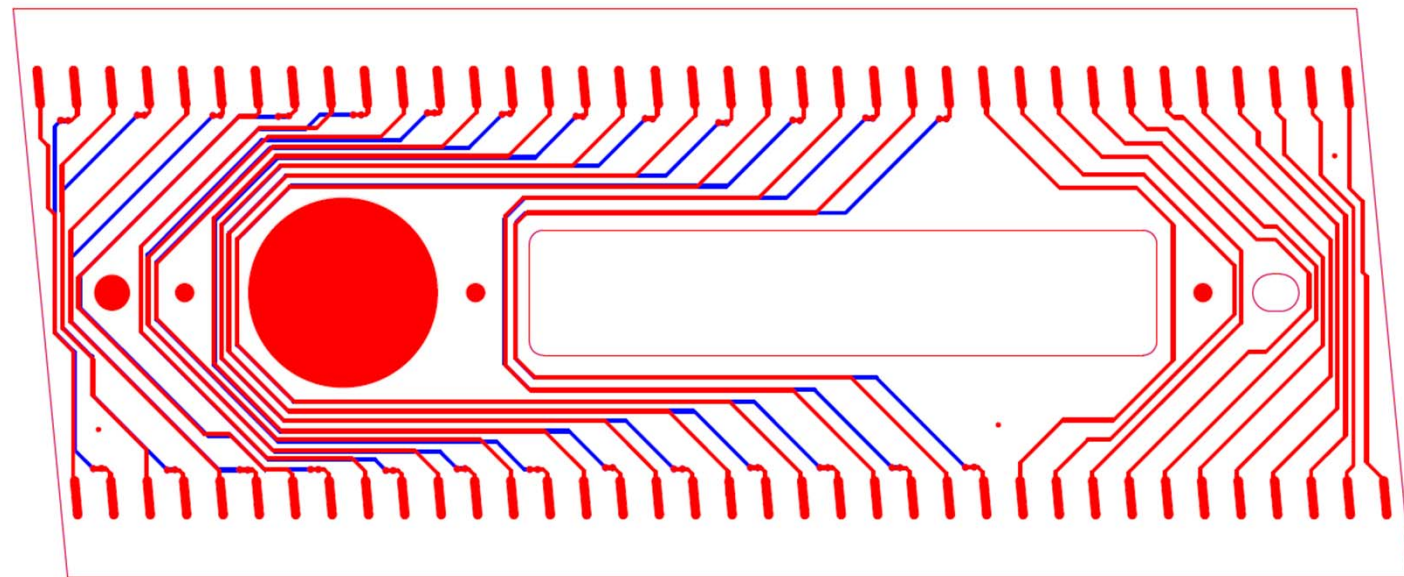
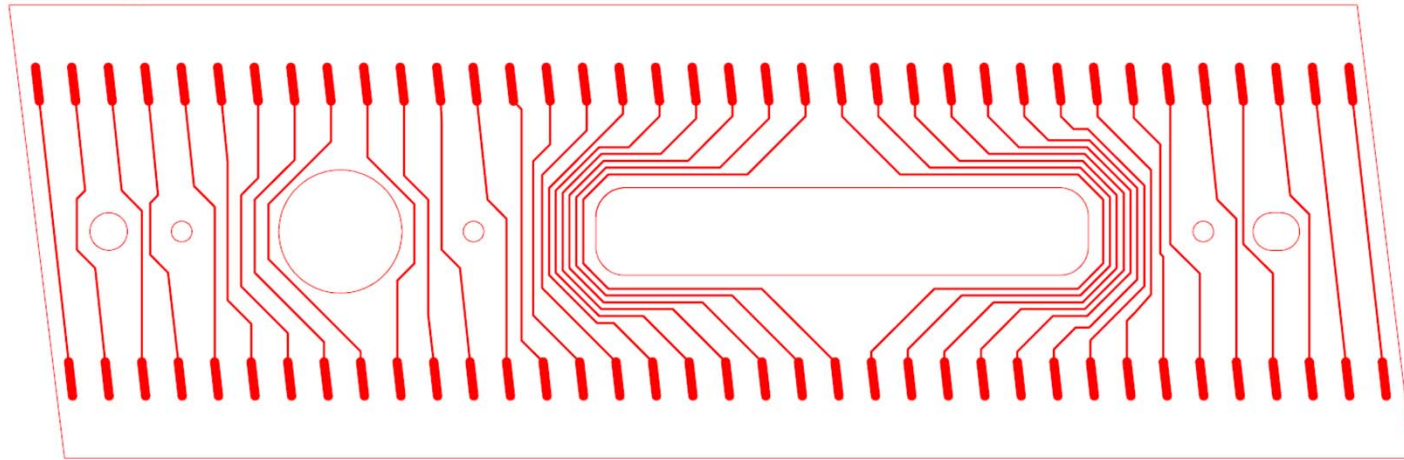
New



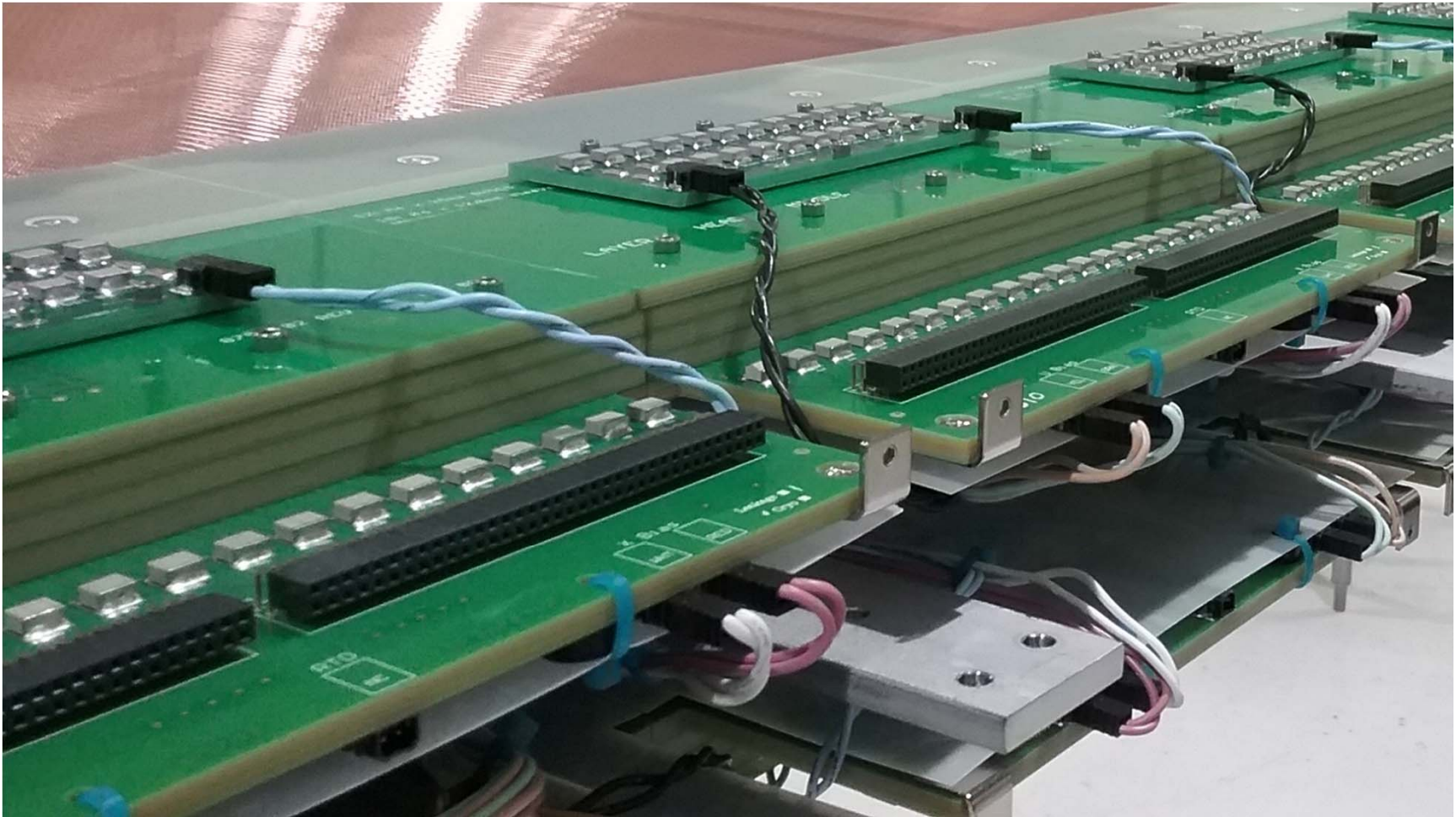
# V-Layer Side Boards



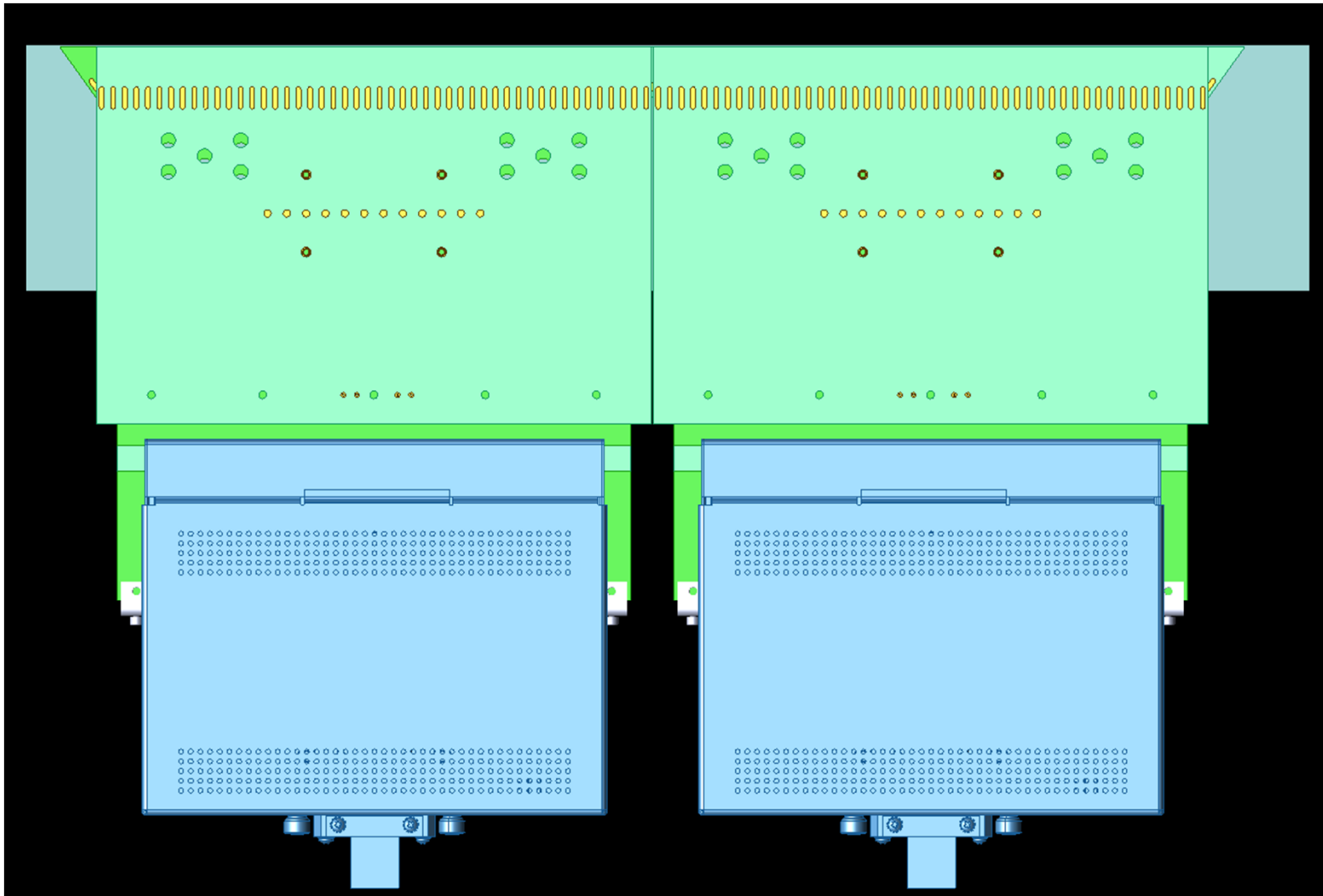
# U-Layer Side Boards



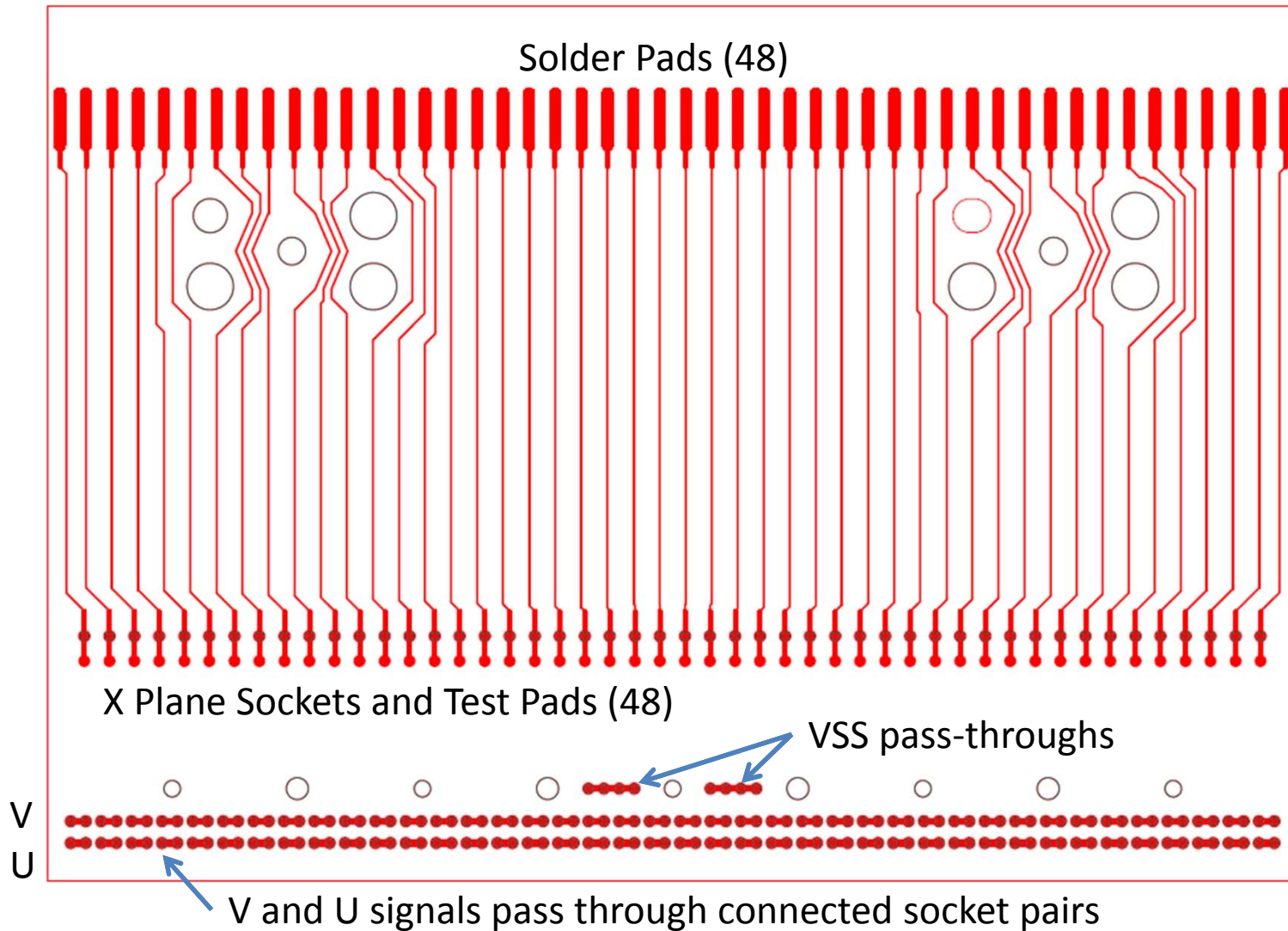
# Head Board Structure



# Slots Between CR Boards



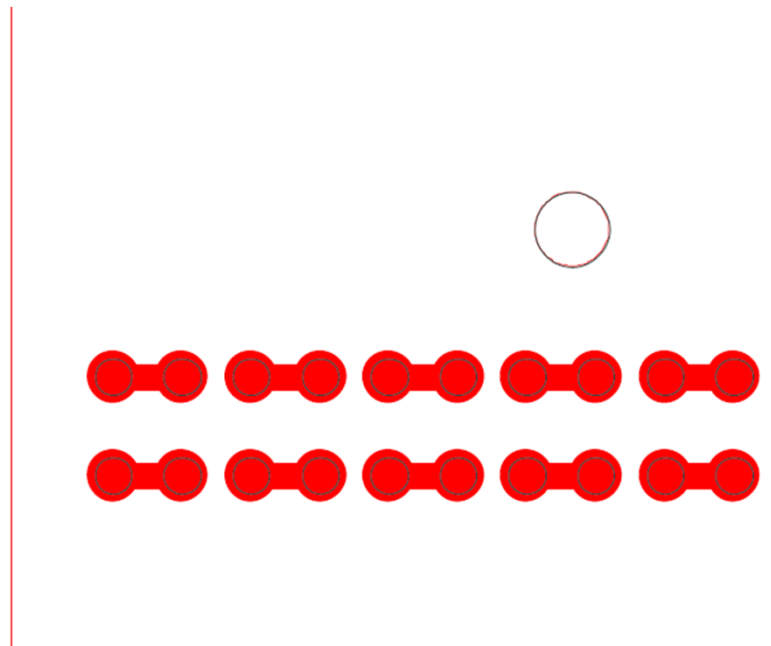
# X-layer Head Board: ProtoDUNE



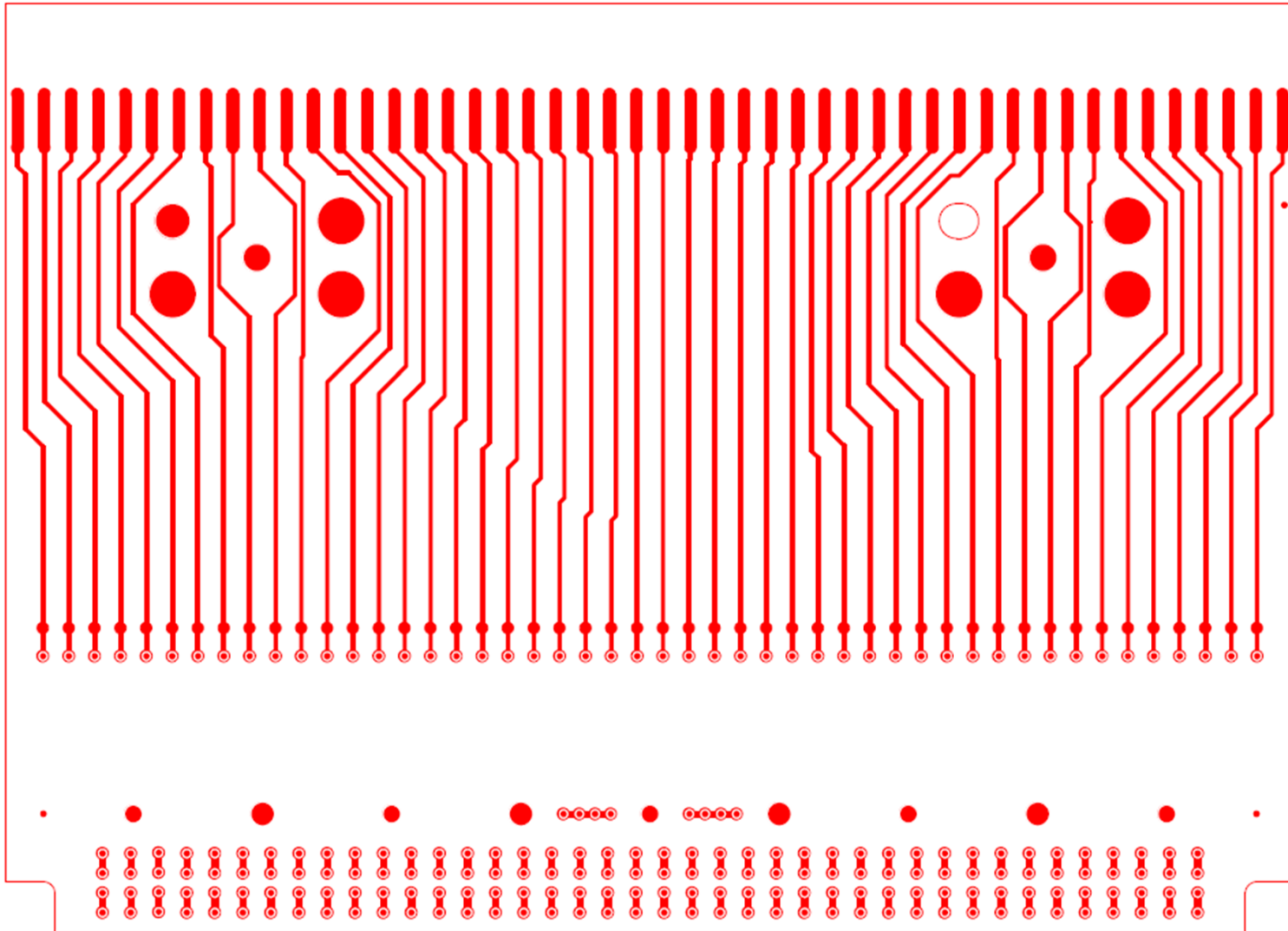


# X-layer Head Board: ProtoDUNE

- Spacing of 0.5 mm between channels limits the safe voltage that can be applied between adjacent wires (~100 V)
- Increased spacing is desired to support voltage differences as high as 400 V

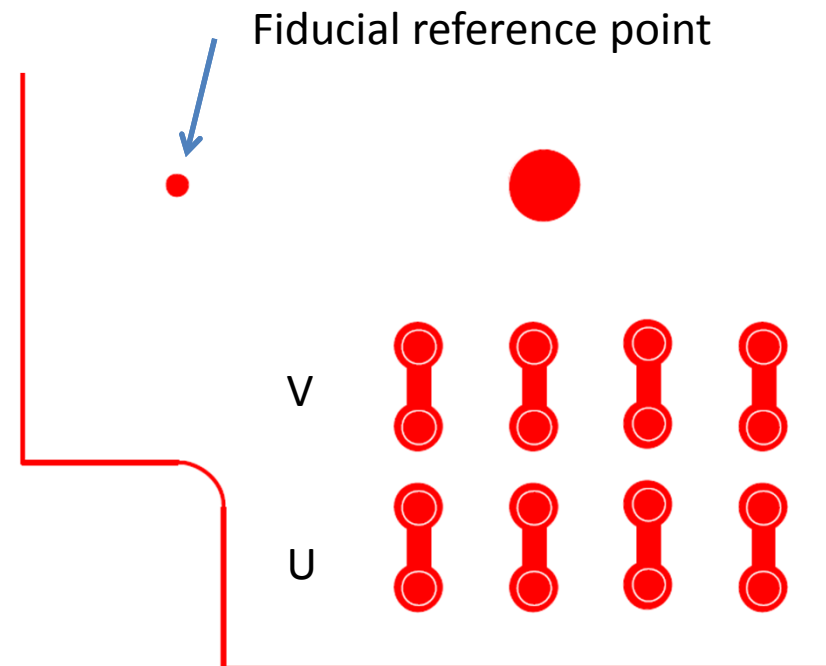


# X-layer Head Board: DUNE



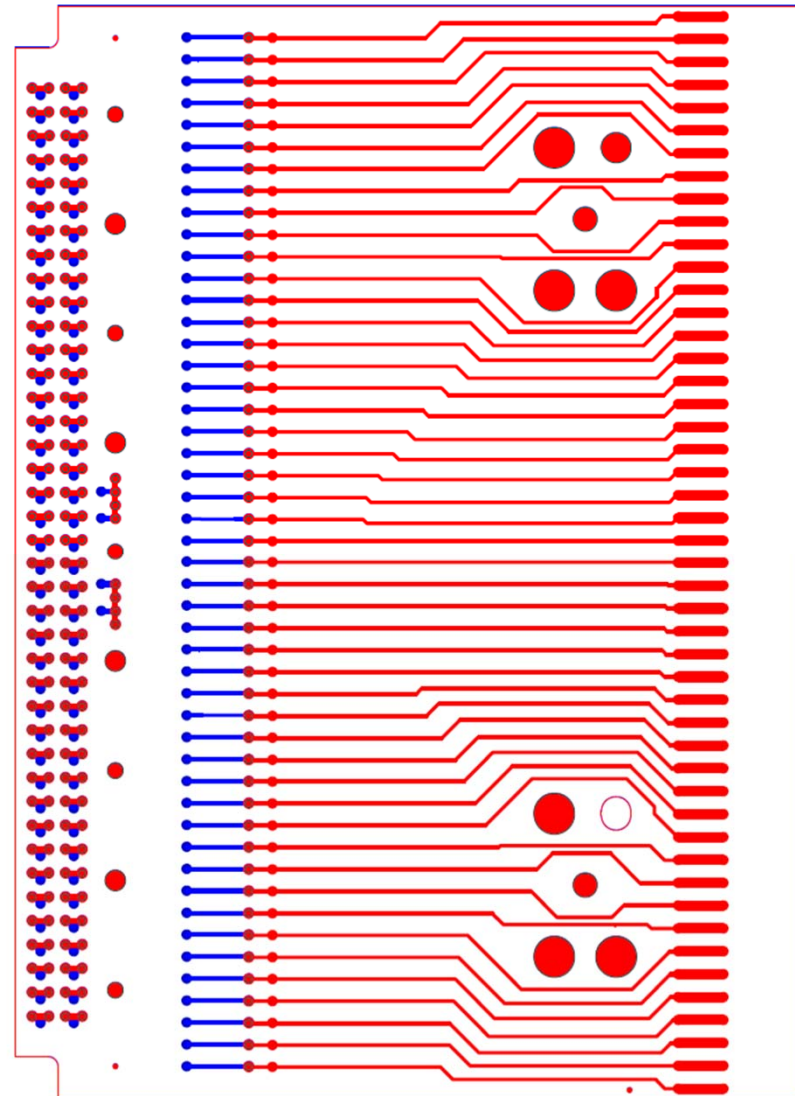
# X-layer Head Board: DUNE

- Spacing between U and V wire channels has increased to 2.5 mm
- Board edge was moved 4.0 mm to accommodate increased channel spacing
- Fiducials were added to all boards to support inspection by automatic vision systems

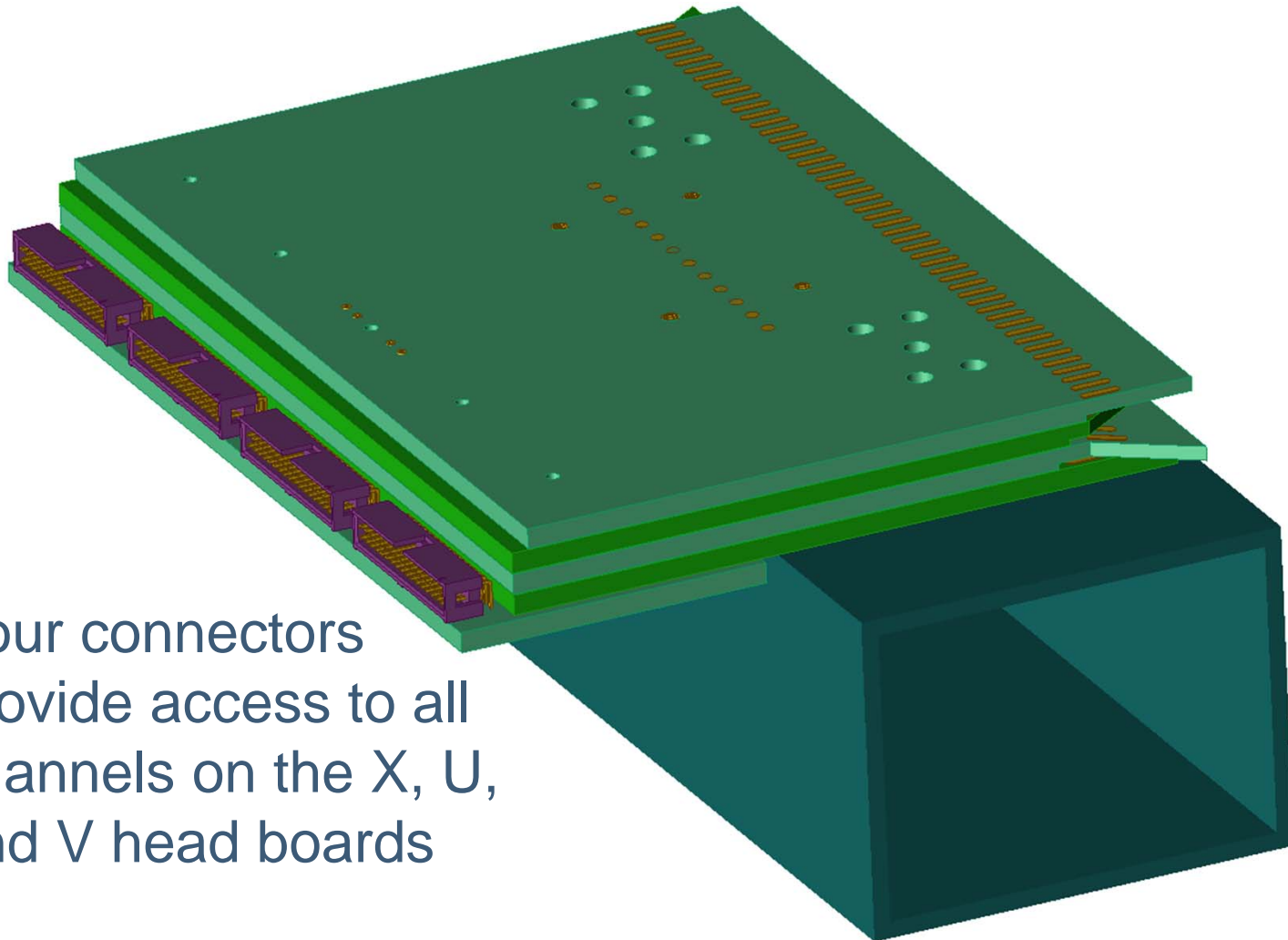


# X-layer Head Board: DUNE

- Landing pads were added to the bottom side of X head boards (blue traces)
- Pads allow the attachment of test headers in place of CR boards
- Headers use spring-loaded contact pins

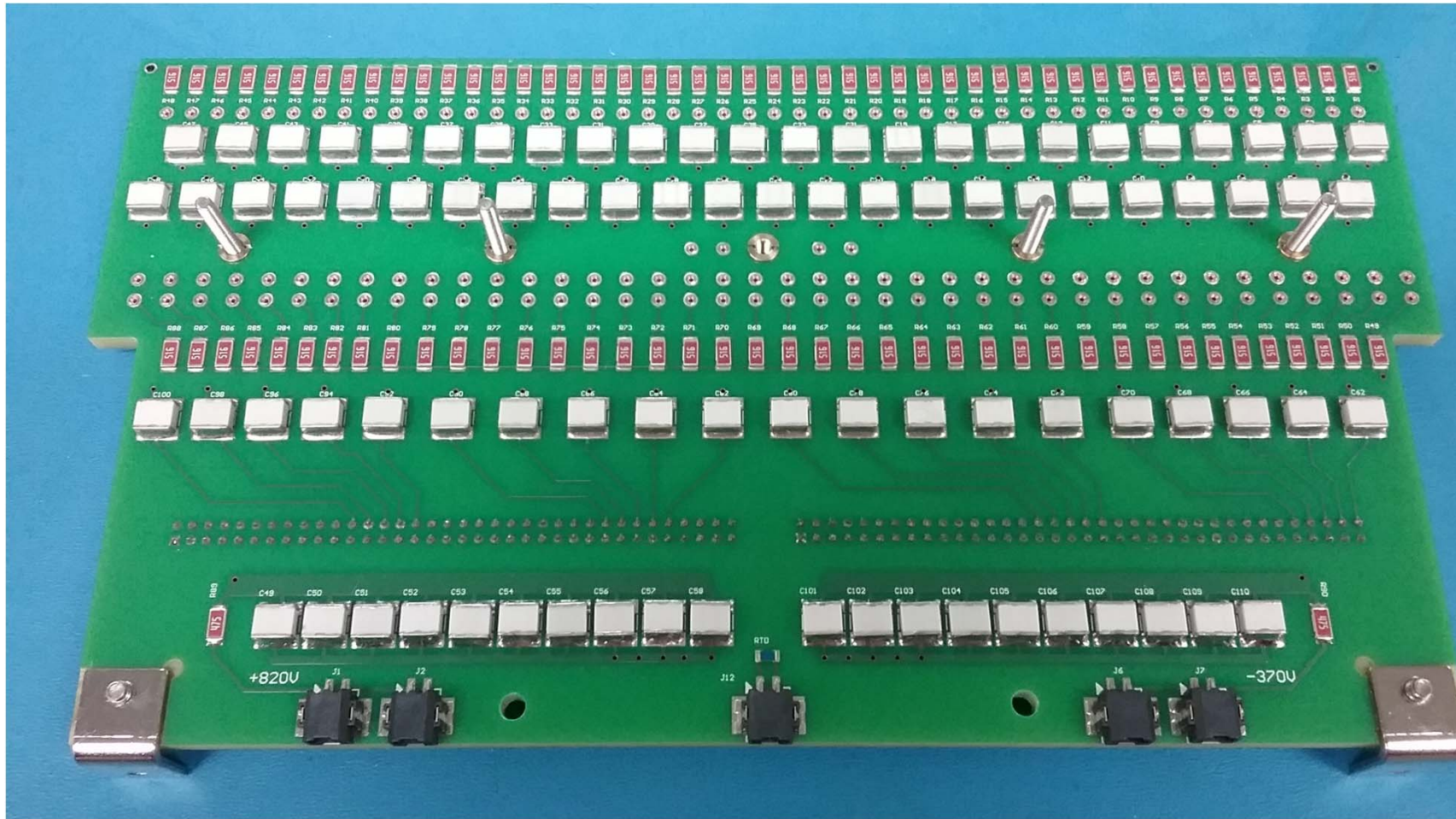


# Test Header Concept



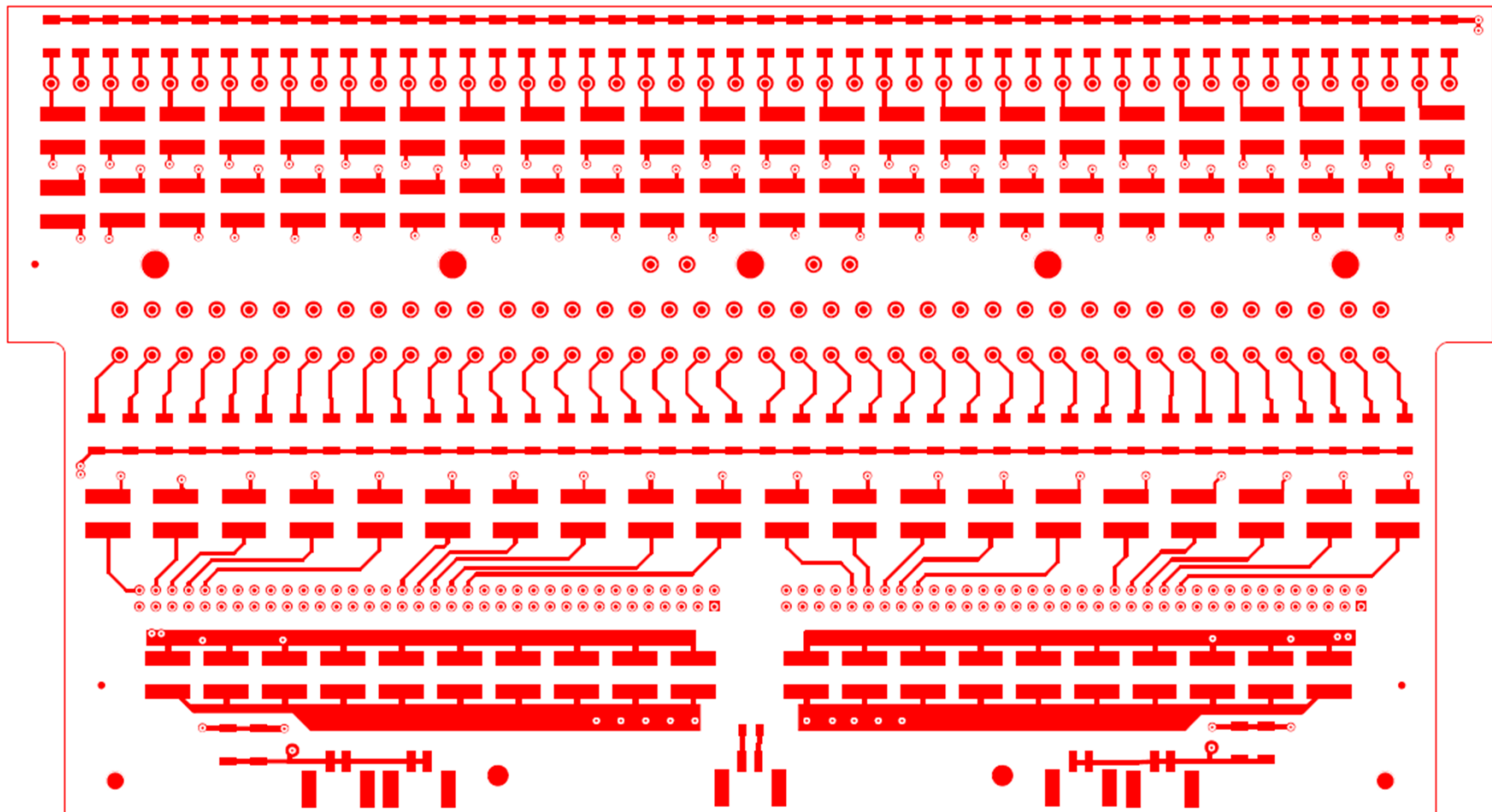
- Four connectors provide access to all channels on the X, U, and V head boards

# CR Board (ProtoDUNE)

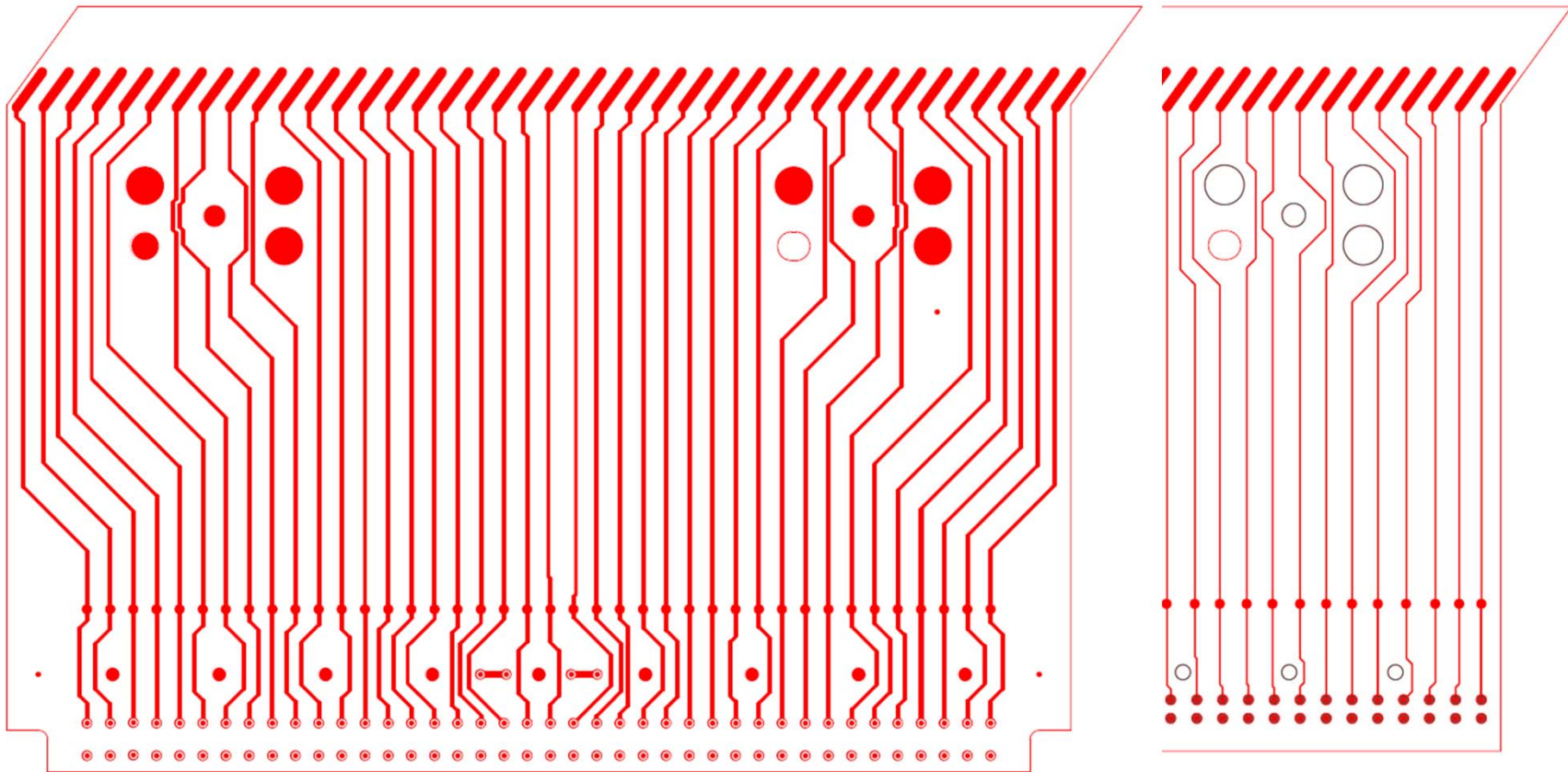


# New CR Board

Minor changes only

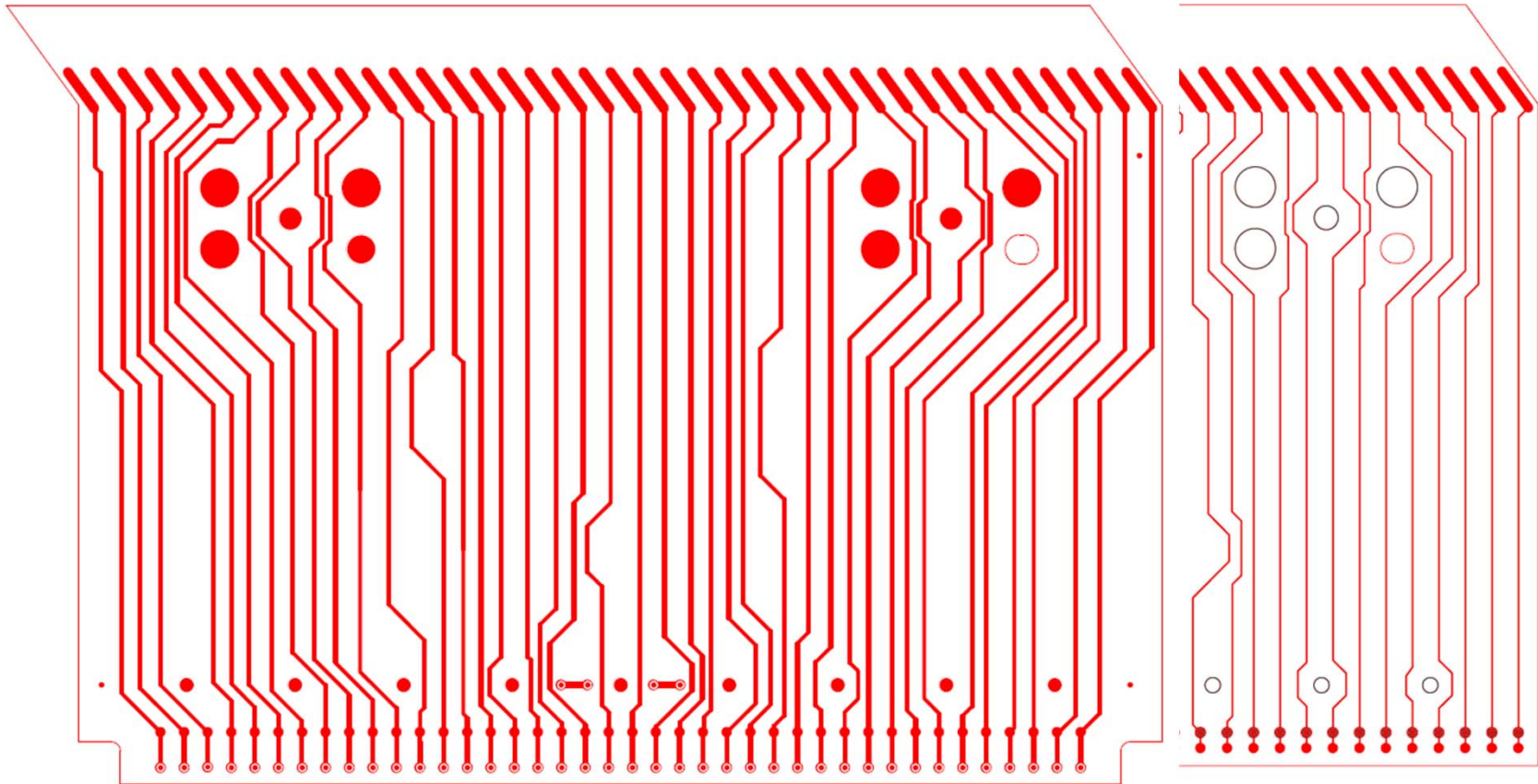


# V-layer Head Boards (new / old)

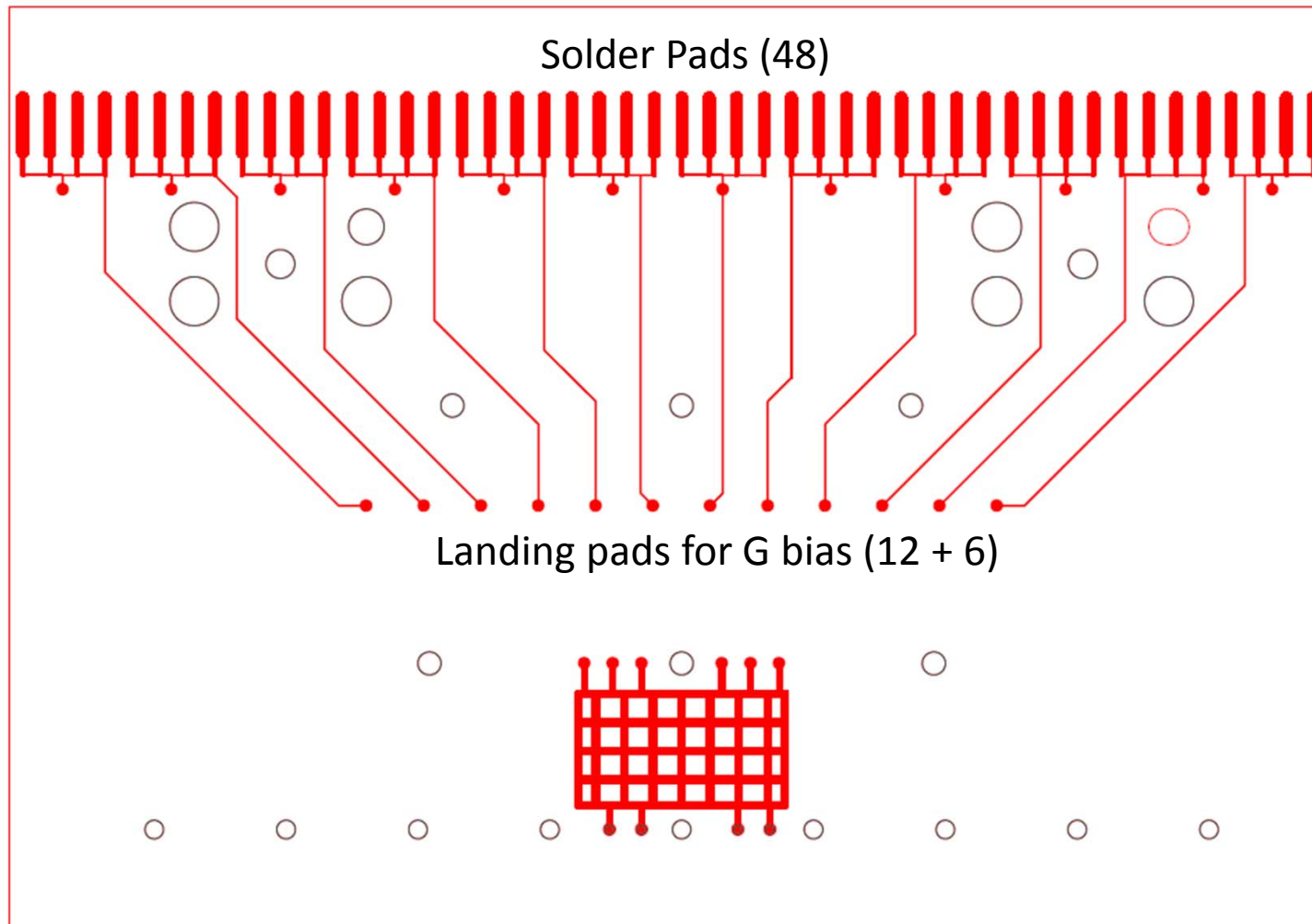




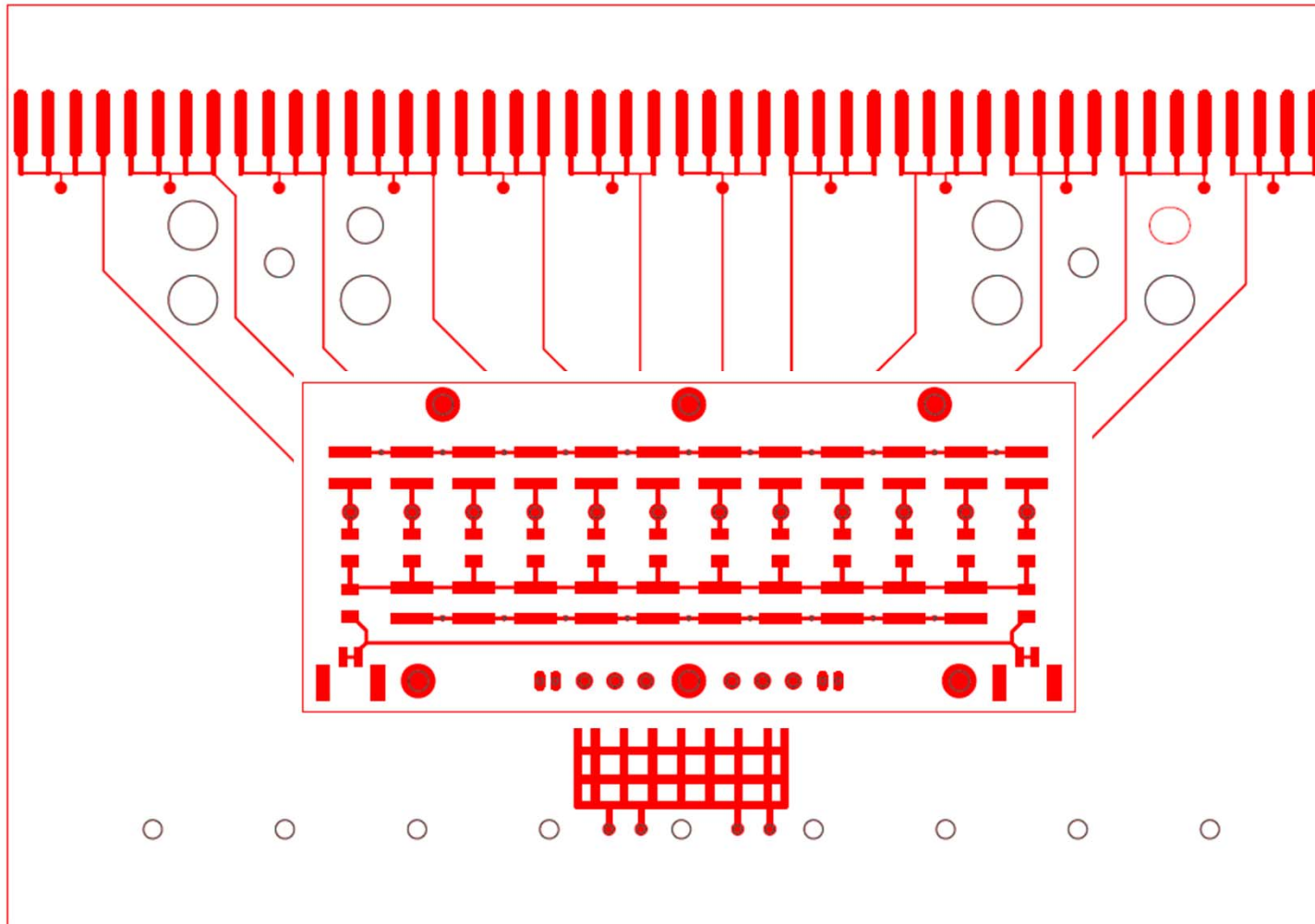
# U Layer Head Boards (new / old)



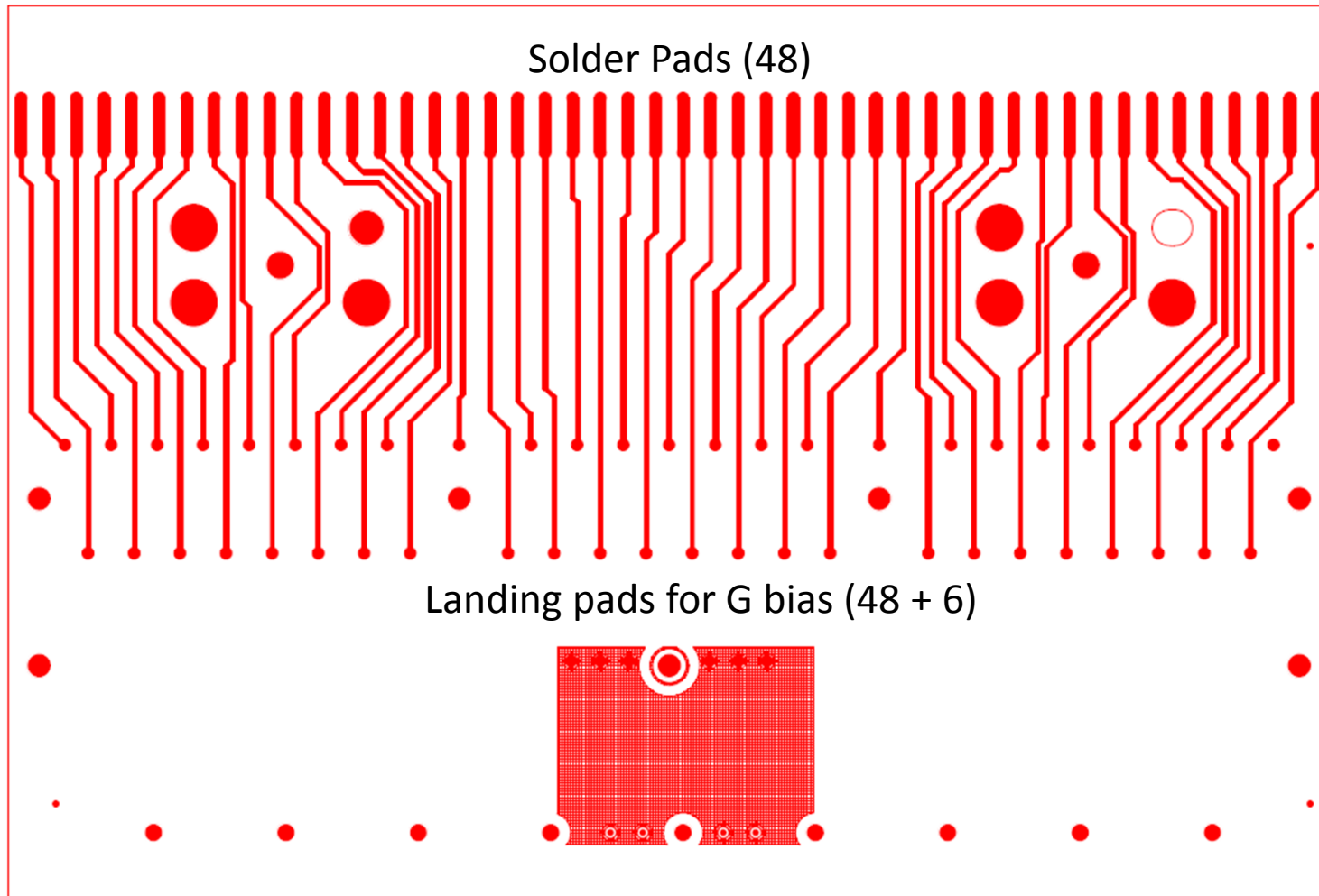
# G Layer Head Board: ProtoDUNE



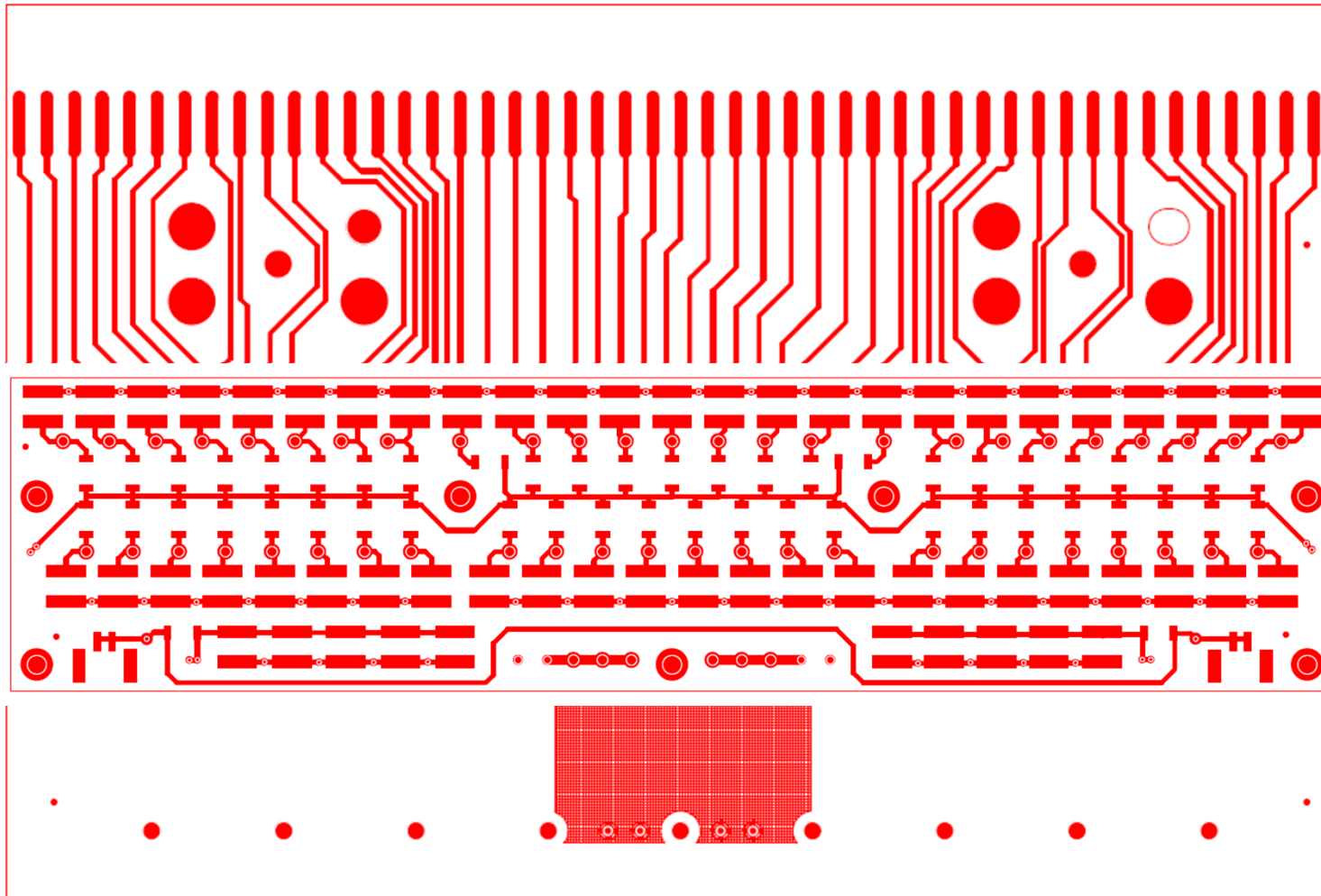
# G Bias Board: ProtoDUNE



# G Layer Head Board: DUNE



# G Bias Board: DUNE



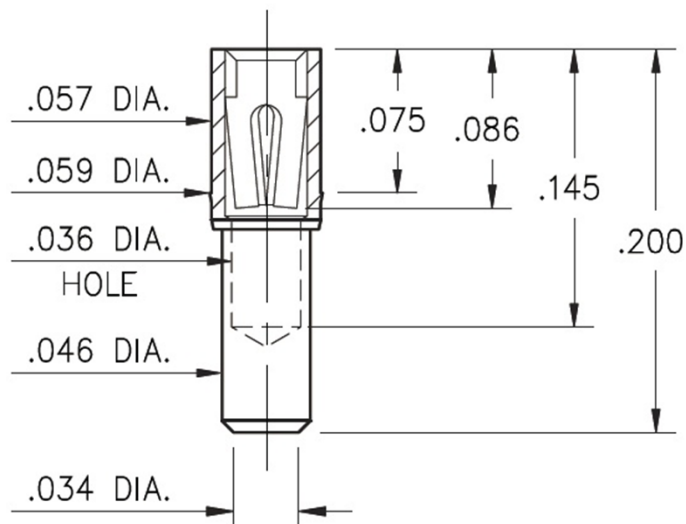
# ProtoDUNE Sockets and Pins

Standard catalog items had some performance issues

## 1701

1701-0-15-XX-30-XX-10-0

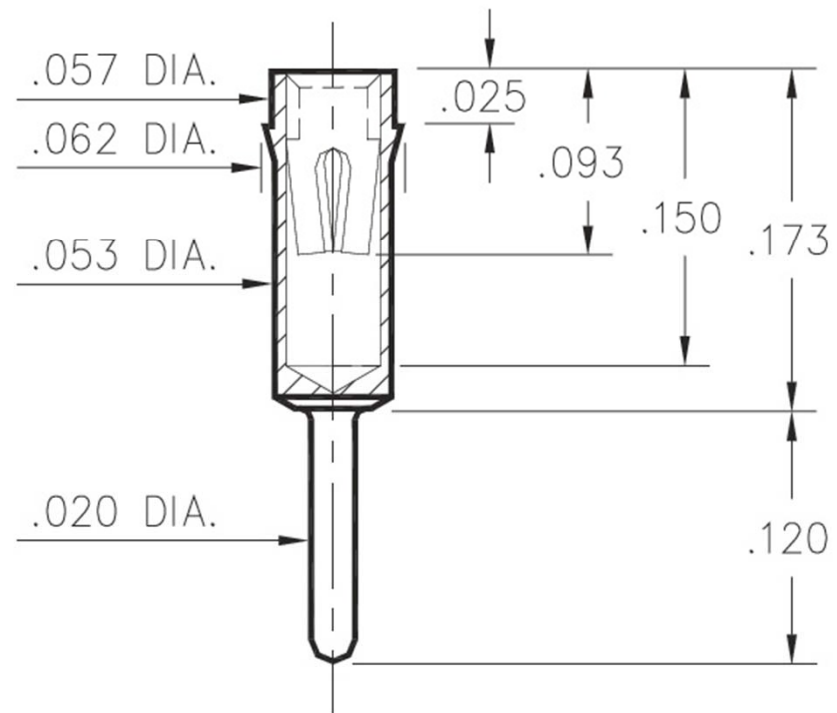
Press-fit in .057 mounting hole



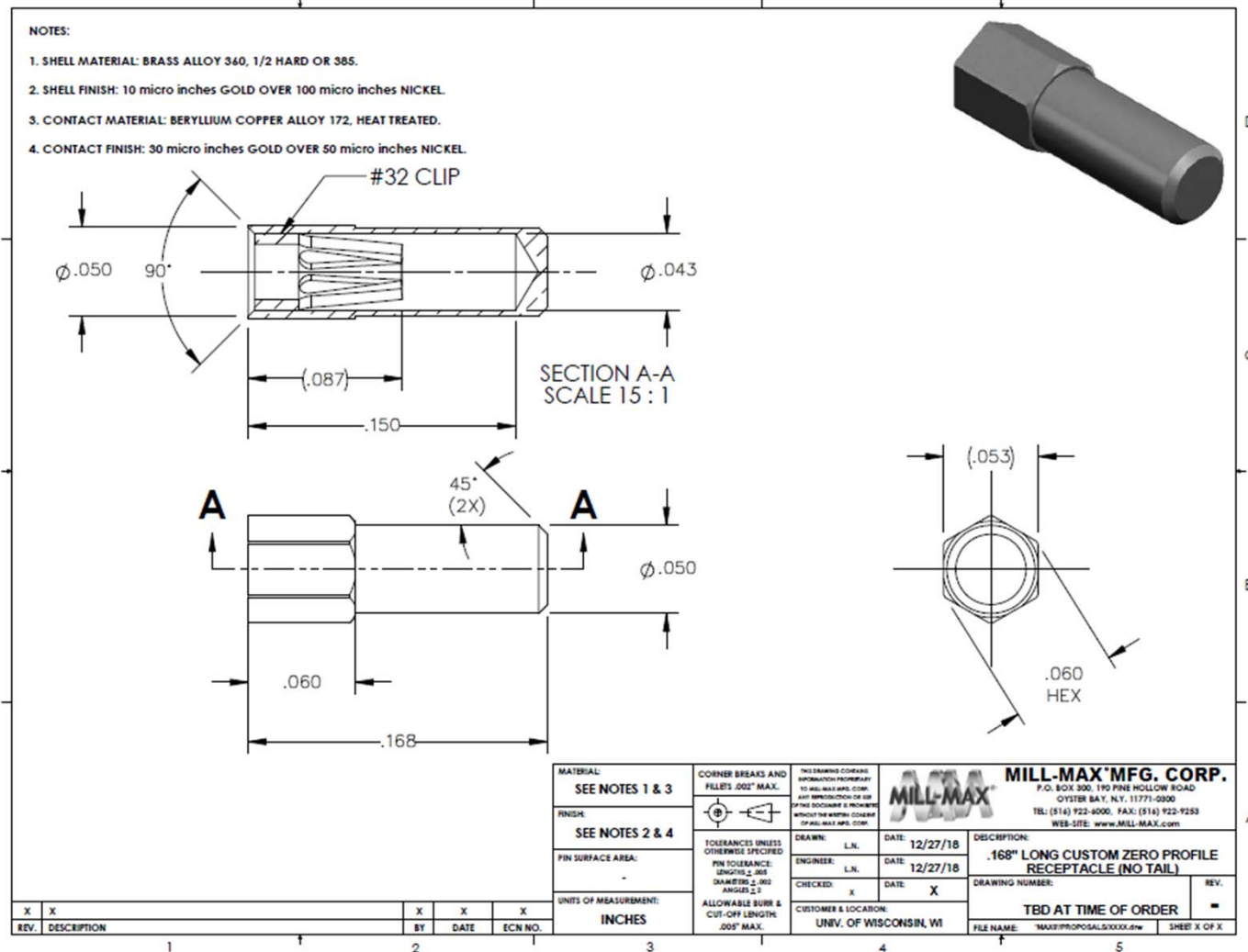
## 0307

0307-0-15-XX-30-XX-04-0

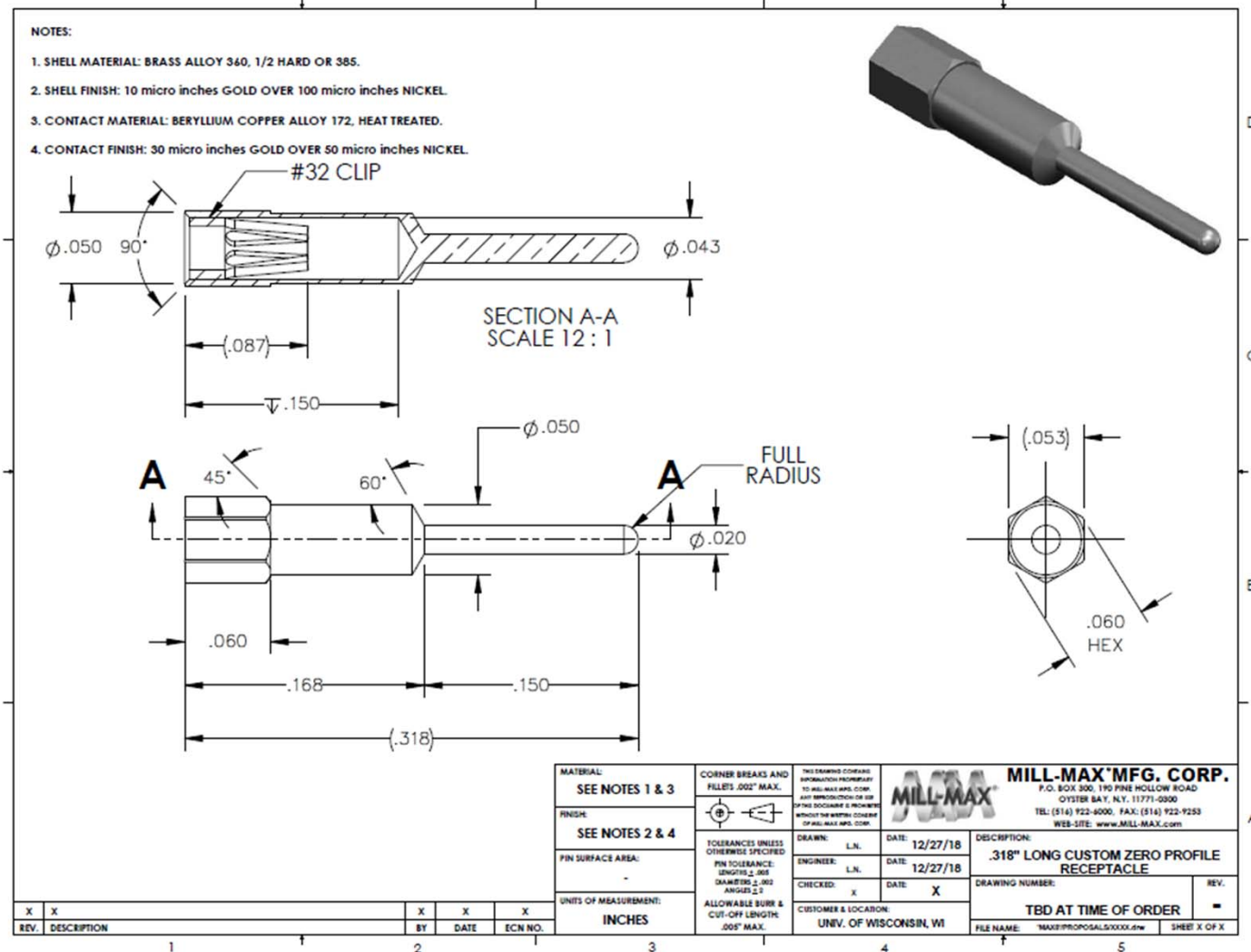
Press-fit in .059 mounting hole



# DUNE Sockets

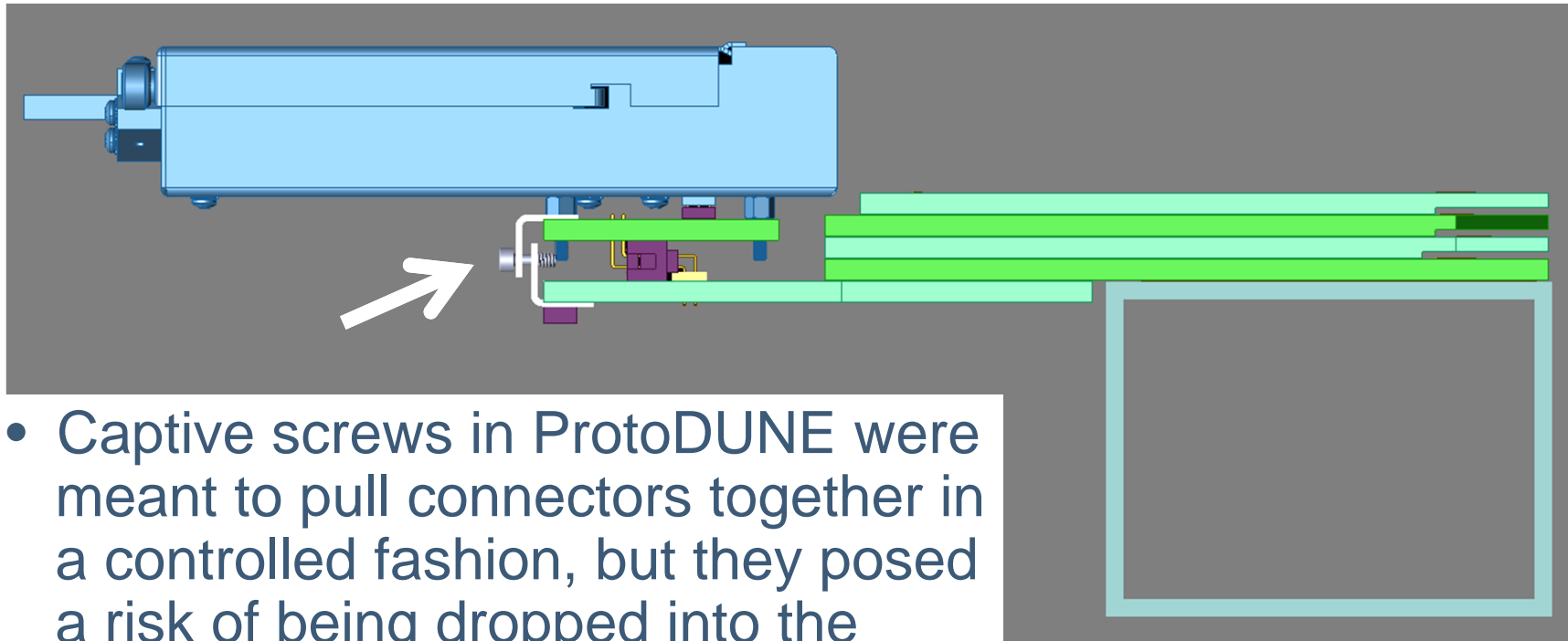


# DUNE Pins



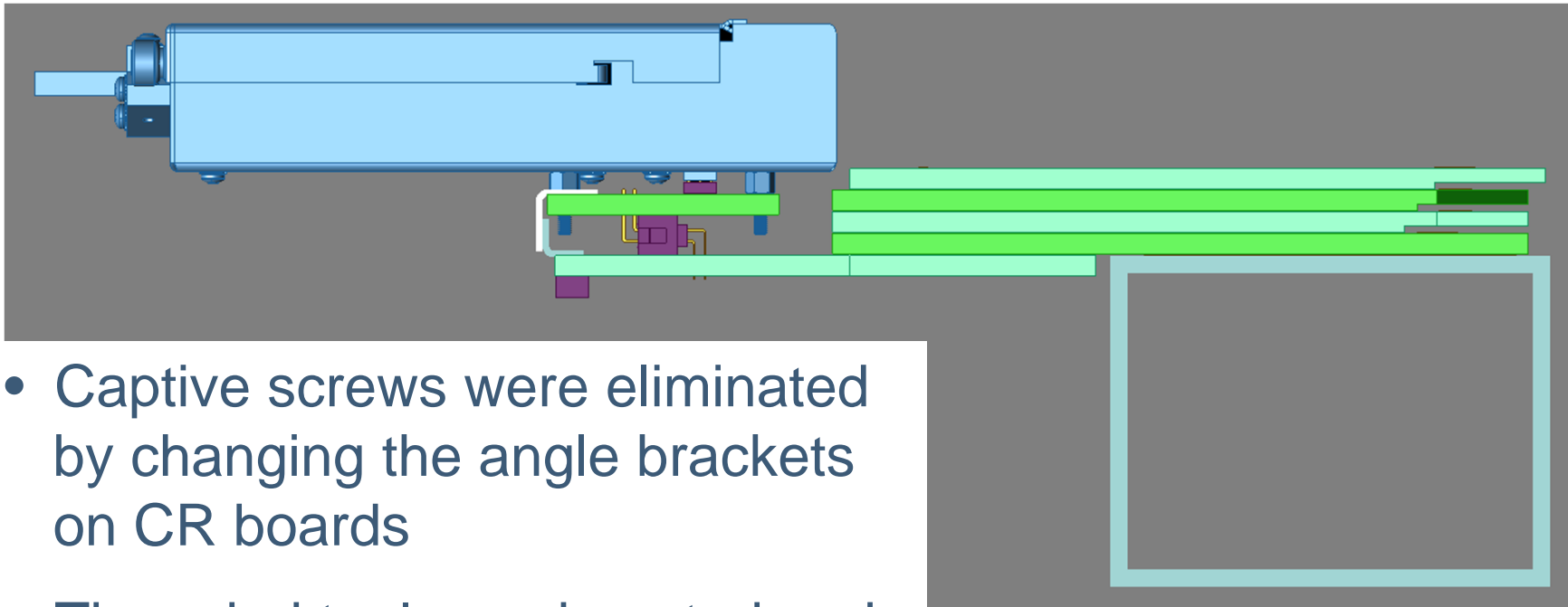


# CE Assembly Installation



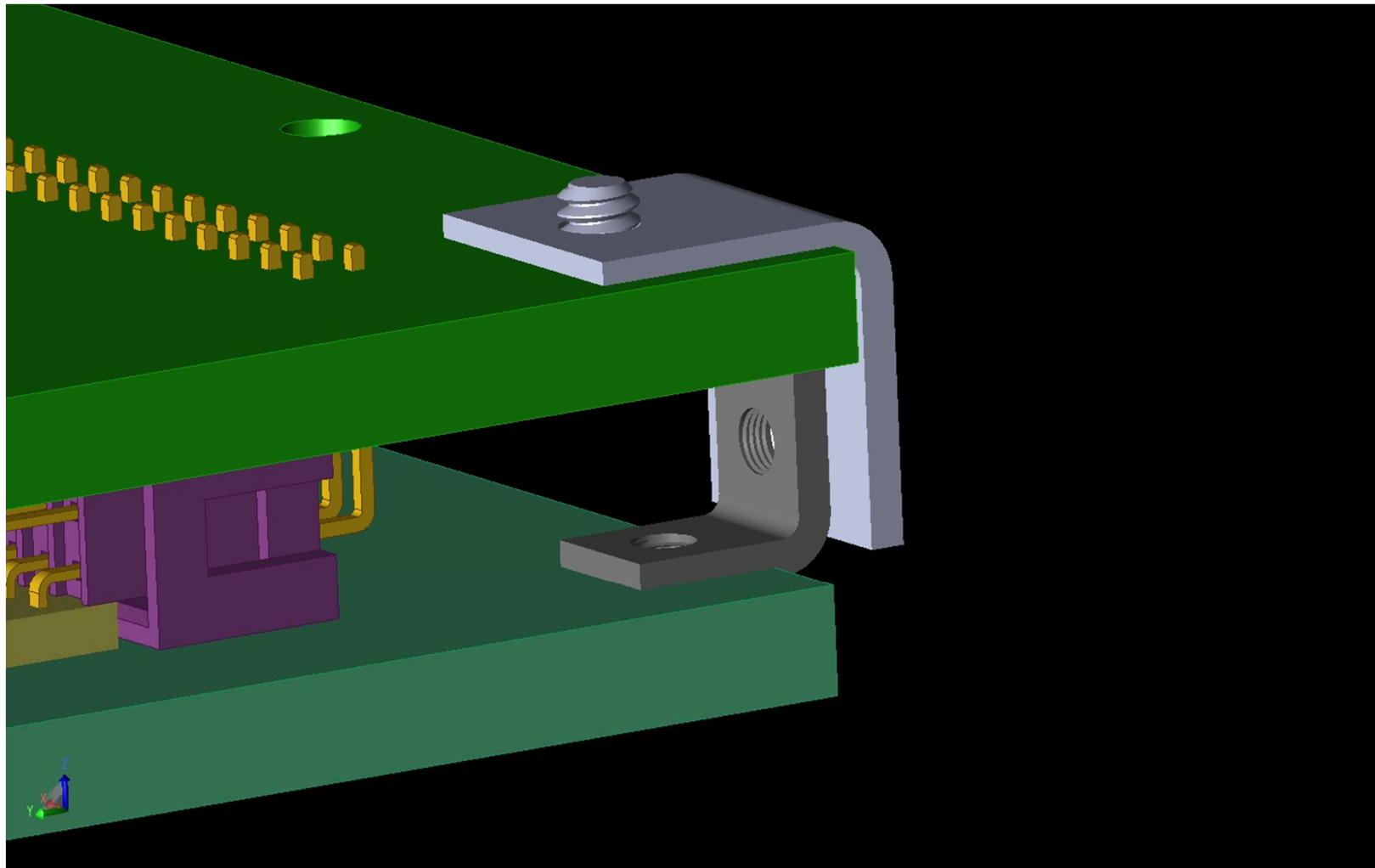
- Captive screws in ProtoDUNE were meant to pull connectors together in a controlled fashion, but they posed a risk of being dropped into the cryostat during CE installation or removal

# CE Assembly Installation



- Captive screws were eliminated by changing the angle brackets on CR boards
- Threaded tools are inserted and rotated to pull connectors together, then removed

# CE Assembly Installation



# Hardware Improvements

- Expanding threaded inserts have been replaced by broaching fasteners to prevent breaking and reduce metal debris



# Process Improvements

- Improved tools and methods are being evaluated for PCBs
  - Instrumented tips on soldering irons for process control
  - Vapor-phase reflow soldering for CR and G Bias boards
  - Improved board-washing equipment
  - Automated test systems for CR boards and G-Bias boards

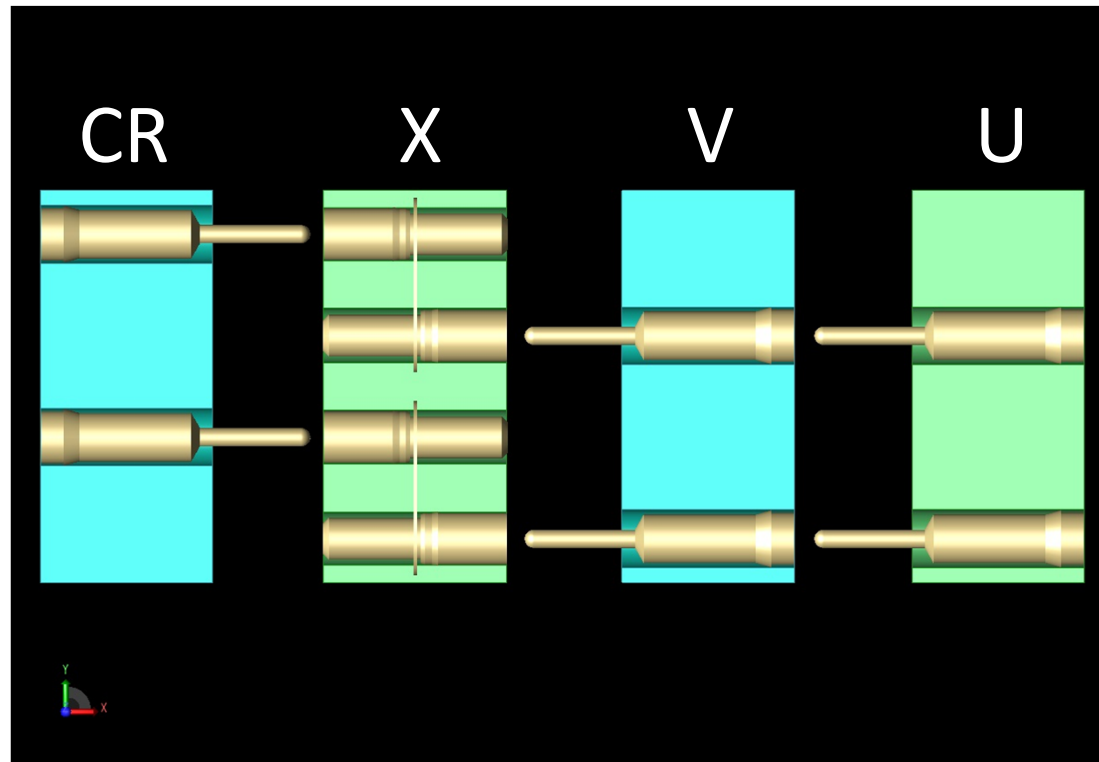
# Quality Assurance and Control

- All ProtoDUNE boards were inspected when received
- Complex mechanical features were frequently out of spec
- Continued inspection of most boards is probably needed
- Manual board inspection was time-consuming
- Vision systems are being evaluated for board inspection

# Backup Slides

# Mill-Max Pins and Sockets

Pins are fragile and not repairable once bent.  
Their exposure is minimized during APA assembly.





In ProtoDUNE the separation between exposed metal through-hole pads is about 0.5 mm.

